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Docket No. SNY- T5463.01

COVER SHEET



To the Assistant Commissioner for Patents. Please record the attached original documents or copies thereof. <u>1.</u> Name of conveying party(ies): 7.9.03 Ryuichi Iwamura 2. Name and address of receiving party(ies): Sony Corporation, a Japanese corporation, 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan and Sony Electronics Inc. a Delaware corporation, 1 Sony Drive, Park Ridge, New Jersey 07656 Nature of Conveyance: [X] Assignment [] Security Agreement [] Merger [] Change of Name [] Other _ Execution Date: 7/7/2003 Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: 7/7/2003 A. Patent application numbers: B. Patent numbers: 5 Name and address of party to whom correspondence concerning document should be mailed: Jerry A. Miller Miller Patent Services 2500 Dockery Lane Raleigh, NC 27606 Phone 919-816-9981 Fax 919-816-9982 Total number of applications and patents involved: Total fee (37 CFR 3.41): \$ 40.00 [] Enclosed [X] Charge to Credit Card. See enclosed credit card authorization. [] Authorized to charge to deposit account. [X] Charge any additional fees required to deposit account. 8. Deposit Account Number: 50-1267 9. Statement and signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Jerry A. Miller, Reg. No. 30,779

Name of Person Signing

Total number of pages including cover sheet:

PATENT TRADEMARK OFFICE

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Assignment Cover Sheet

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in Carrier Management for a Network for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan and Sony Electronics Inc. a Delaware corporation with offices at 1 Sony Drive, Park Ridge, New Jersey 07656 (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

And I hereby authorize and request my attorney(s) of record in this number and filing date of this application in the spaces that follow: Serial N	
ridinaci and filing date of this application in the spaces that follow. Serial N	lumber:, Filing Date:
This assignment executed on the dates indicated below.	
The assignment excepted on the dates indicated below.	Tho
Ryuichi lwamura	× 1/11/1/ 7.023
Name of first inventor	Execution date of U.S. Patent Application
San Diego, CA	
Residence of first or sole inventor	
× Bartonn	July 7, 2003
Signature of first inventor	Date of this assignment
	Date of the designment
K.E. Sonks	
Witness Name	
X HE Sanas	V 7/7/03
Witness Signature	Date

Sony Assignment